



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-09-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	C107*FL6CA3F	A	Z8GA	2014-09-26
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package:SO 08 .15 JEDEC; MDF for STS5NF60L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	C107*FL6CA3F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	3.044	mg	supplier	die	Silicon (Si)	7440-21-3		2.983	mg	979961	37288
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.02	mg	6570	250
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	1314	50
Die Attach				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.012	mg	3942	150
Die Attach				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	329	13
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1314	50
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.02	mg	6570	250
Leadframe	Copper & its alloys	31.241	mg	supplier	alloy	Copper(CU)	7440-50-8		30.209	mg	19159	12
Leadframe				supplier	alloy	Iron(Fe)	7439-89-6		0.729	mg	1545	1
Leadframe				supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.026	mg	7726	5
Leadframe				supplier	alloy	Zinc(Zn)	7440-66-6		0.039	mg	994375	465487
Leadframe				supplier	metallization	Silver(Ag)	7440-22-4		0.238	mg	1062	497
Die attach	Other inorganic materials	0.326	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.284	mg	4245	1987
Die attach				supplier	glue or tape	Bismaleimide resin	Proprietary		0.02	mg	318	149
Die attach				supplier	glue or tape	Isobornyl Methacrylate	7534-94-3		0.02	mg	935037	3482
Die attach				supplier	glue or tape	polymer	Proprietary		0.002	mg	14975	56
Bonding wire	Other inorganic materials	0.079	mg	supplier	wire	Copper(CU)	7440-50-8		0.079	mg	49987	186
encapsulation	Other inorganic materials	41.52	mg	supplier	mold compound	Epoxy Resin	Proprietary		3.115	mg	1000000	382
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		2.077	mg	756667	420037
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		35.955	mg	127827	70959
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.207	mg	71015	39422
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.166	mg	20290	11263
connections coating	Solder	3.79	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.79	mg	20142	11181